Doc. No. : PCN240601
Date : Jun 24, 2024

To : Dear Valued Customers

Product/Process Change Notice

We hereby submit PCN for your review and approval.

Application or type：

The product add new assembly site.

Detail of the change：

The manufacturing sites are existing qualified suppliers of Comchip.

Reason for the change：

This notification is to advise our customers that we will add the new assembly site of the following product to better support long-term demand for the affected products.

Full electrical characterization and reliability testing have been completed on representative part numbers to ensure there is no change to device function or electrical specifications in the datasheet.
Reliability reports as attached file.

Evaluation items：

Part No.	Package Type
(A)CGRA4001-HF Thru. (A)CGRA4007-HF	SMA/DO-214AC
CPDVR105V0UA-HF	DFN2510-10L

* Subject to ROHS product material survey table final confirmation.

Implemented from：

Effective immediately.

R&D Dept. Signature：	QA Dept. Signature：
	Kevin Tseng

Answer To PCN

Please complete the form below duly signed and fax back to Comchip Technology Co.

Please select your answer 1. Approved this PCN 2. Approved this PCN with conditions 3. Disapproved this PCN	Date
	Responsibility By
Please specify the condition or explain the reason if you select 2 or 3.	

Unless a Comchip Technology Co., Ltd. Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.

Technology Co., Ltd.

Reliability Test Report

Product.: **Part No. affected**

Doc. No. **PCN240601**

Date: 2024.05.24

ComChip Technology Co., Ltd.

Add.：No. 586, Jianguo Rd., Yingge Dist.,
New Taipei City 23943, Taiwan

Tel.：886-2-8677-6675
FAX：886-2-8677-6672

QR-0803-02 Rev.G

Comchip Technology Co., Ltd.

Discrete Semiconductor Component Qualification Plan

Supplier Internal P / N ： Part No. affected
Supplier： Comchip
User Component Engineer： Judy Lin
General Specification： AEC-Q101 Rev-E Table 3: Process Change Guidelines for the Selection of Tests
Supplier Manufacturing Site： Yingge, Taiwan

Date： 2024/5/24
Doc. No.： PCN240601

Item	Test	Test Conditions	Test Foundation	S. S.	Remarks
1	TEST	Electrical characterization @25C	SPEC.	505	PASS
2	Preconditioning	Ta= 125℃ Time= 24 hrs Ta= 85 ℃ RH= 85% Time = 168 hrs 3 reflow cycles	JESD22 A-113	231	PASS
3	External Visual	per AEC-Q101	SPEC.	505	PASS
4	HTRB	Reverse Biased @ 100% V Ta= Tj. Test Time=1000 hrs	MIL-STD-750 M1038 Method A	77	PASS
5	Temperature Cycling	Tamin = -55℃ to Tamax150℃ dwelled for 25 min, transfer time=5min, Cycle = 1000	JESD22 A-104	77	PASS
5	Unbiased Highly Accelerated Stress	Ta= 130 ℃, RH= 85% Test Time=96 hrs	JESD22 A-118	77	PASS
6	Autoclave	Ta = 121℃, P = 15psig, RH = 100% Test Time=96hrs	JESD22 A-102		
7	H3TRB	Reverse Biased @ 80% V (MAX 100V) Ta= 85 ℃, RH= 85% Test Time=1000 hrs	JESD22 A-101	77	PASS
8	HTSL	Ta= Tstg max℃. Time= 1000 hrs	JESD22 A-103	77	PASS
9	ESD	CDM: 1 KV HBM: 1 KV	AEC Q101-001 and 005	60	PASS
10	Physical Dimension	per AEC-Q101	JESD22 B-100	30	PASS
11	Resistance to Solder Heat	Solder Pot Temp. 260±5℃ Duration 4-6 sec	JESD22 A-111	30	PASS
12	Solderability	Solder Pot Temp. 245±5℃ Duration 5-10 sec	JESD22 B-102	10	PASS
13	Thermal Resistance	per AEC-Q101	JESD24-3, 24- 4, 24-6 as appropriate	10	PASS

Conclusion:

1. The total test had 13 item of reability test.
2. There were test result of pass.

Approval: Zeus Lai

Prepare: Judy Lin

Comchip SMD Diode Specialist **Technology Co., Ltd.**

Reliability Test Report

Part NO.: Part No. affected
Diodes

Doc. No. PCN240601

Date: 2024.05.27

ComChip Technology Co., Ltd.

Add.：No. 586, Jianguo Rd., Yingge Dist.,
New Taipei City 23943, Taiwan

Tel.：886-2-8677-6675

QR-0803-02 Rev.G

Date: 2024/5/27

Reliability Test Summary

P / N ： Part No. affected

Doc. No. : PCN240601

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Test Results
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5℃ Time= 5~10 sec.	MIL-STD-750 Method 2026	0	22	PASS
2	Soldering Heat	Temp of solder pot=260±5℃ Time= 10~12 sec	MIL-STD-750 Method 2031	0	22	PASS
3	Temperature Cycle	Low Tstg to High Tstg dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750 Method 1051	0	22	PASS
4	High Temperature Reverse Bias Life	VR= VR*80% Temp.(depend on product) Time 168hrs.	MIL-STD-750 Method 1038	0	22	PASS
5	Pressure Cooker Test	Ta= 121℃ Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	0	22	PASS
6	High Temperature Storage Life	Ta= High Tstg. Time= 168 hrs	MIL-STD-750 Method 1031	0	22	PASS
7	Humidity	Ta= 85 ℃ RH= 85% Time=168 hrs	EIAJ ED-4701	0	22	PASS

Conclusion:

1.共有 7 項實驗

2.測試結果：PASS

Approval: Zeus Lai

Prepare: Judy Lin